



# 100% Material Declaration Data Sheet for 7 Series CLG225 Package

PK612 (v1.0) July 5, 2013

**Average Weight: 0.4710 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.014830</b>	<b>3.149%</b>
	Silicon	7440-21-3	100.00		0.014830	
<b>Die Attach</b>					<b>0.003759</b>	<b>0.798%</b>
	Silver	7440-22-4	77.50		0.002913	
	Bismaleimide monomer	Trade Secret	15.00		0.000564	
	Acrylate monomer	Trade Secret	7.50		0.000282	
<b>Mold Compound</b>					<b>0.220830</b>	<b>46.885%</b>
	Epoxy Resin	Trade Secret	5.00		0.011042	
	Phenol Resin	Trade Secret	3.00		0.006625	
	Phenol Novolac	9003-35-4	3.00		0.006625	
	Metal Hydroxide	Trade Secret	3.00		0.006625	
	Carbon Black	1333-86-0	0.30		0.000662	
	Silica fused	60676-86-0	70.40		0.155464	
	Silica fused	7631-86-9	15.00		0.033125	
	Silica, crystalline	14808-60-7	0.30		0.000662	
<b>Copper Wire</b>					<b>0.003519</b>	<b>0.747%</b>
	Copper	7440-50-8	98.25		0.003457	
	Palladium	7440-05-3	1.75		0.000062	
<b>Solder Balls</b>					<b>0.055691</b>	<b>11.824%</b>
	Tin	7440-31-5	96.50		0.053742	
	Silver	7440-22-4	3.00		0.001671	
	Copper	7440-50-8	0.50		0.000278	
<b>Substrate</b>					<b>0.172371</b>	<b>36.597%</b>
	Copper	7440-50-8	45.65		0.078681	
	Nickel	7440-02-0	1.78		0.003075	
	Gold	7440-57-5	0.30		0.000524	
	Glass Fiber	65997-17-3	20.46		0.035268	
	BT Core	Trade Secret	25.01		0.043106	
	Solder Mask	Trade Secret	6.80		0.011717	

© Copyright 2013 Xilinx, Inc. XILINX, the Xilinx logo, Virtex, Spartan, ISE, and other designated brands included herein are trademarks of Xilinx in the United States and other countries. All other trademarks are the property of their respective owners

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
07/05/13	1.0	Initial Xilinx release.

---

## Notice of Disclaimer

Xilinx regards this materials data to be correct but makes no guarantee as to its accuracy or completeness, including, but not limited to, with respect to its compliance with applicable environmental laws and regulations. Xilinx subcontracts the production, test and assembly of hardware devices to independent third-party vendors and materials suppliers (“Contractors”). All data provided hereunder is based on information received from Contractors. Xilinx has not independently verified the accuracy or completeness of this information which is provided solely for your reference in connection with the use of Xilinx products.